EUROPEAN PATENT OFFICE

Patent Abstracts of Japan

PUBLICATION NUMBER

05198958

PUBLICATION DATE

06-08-93

APPLICATION DATE

20-01-92

APPLICATION NUMBER

04007108

APPLICANT: FUJITSU LTD:

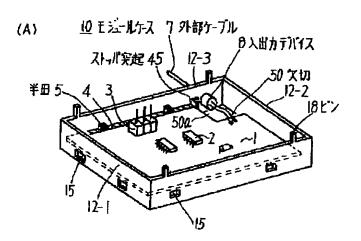
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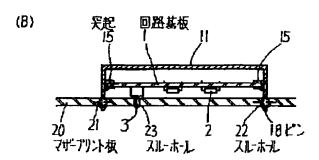
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TITLE

: ELECTRONIC CIRCUIT MODULE





ABSTRACT:

PURPOSE: To eliminate a need for a nickel plating operation by a method wherein a stopper protrusion which sets the correlational position between a circuit board and a module case to be definite is installed at a case sidewall after it has been struck out.

CONSTITUTION: A hole is made in a position corresponding to a cutout 50 in a case sidewall 12-3 at which a stopper protrusion 45 has been installed. A main body part is fitted and inserted into the hole; it is made to protrude to the inside of a module case 10; it is fixed to the case sidewall 12-3. A circuit board 1 is housed in the module case 10 in such a way that it is horizontal, that an input/output terminal 3 is faced upward, that a side edge on the side opposite to the cutout 50 comes into contact with a case sidewall 12-1 and that a cutout-part side edge 50a comes into contact with the stopper protrusion 45. Peripheral edge parts on the rear are brought into contact with and supported by the surface of protrusions 15. A grounding pattern 4 formed at the peripheral edge of the circuit board 1 is soldered to the inner face of the case sidewall. Thereby, the circuit board 1 is fixed and bonded to the module case 10. After that, a lead for an input/output device 8 is soldered to a pattern on the circuit board 1.

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